

Introduction to CMOS VLSI Design

Flash (12.4.3 p.531)

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Modified from slides by Jay Brockman 2008, 2015,2018

[Including slides from Harris & Weste, Ed 4,

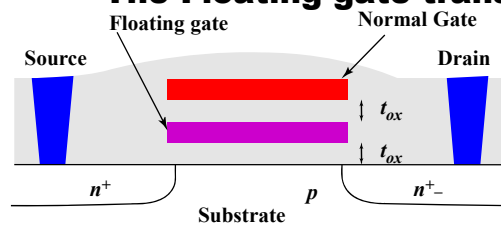
Adapted from Mary Jane Irwin and Vijay Narananan, CSE Penn State
adaptation of Rabaey's *Digital Integrated Circuits*, ©2002, J. Rabaey et al.]

Memory A

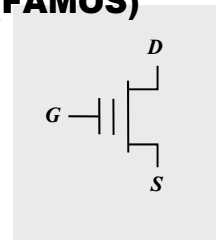
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Slide 1

Non-Volatile Memories The Floating-gate transistor (FAMOS)



Device cross-section



Schematic symbol

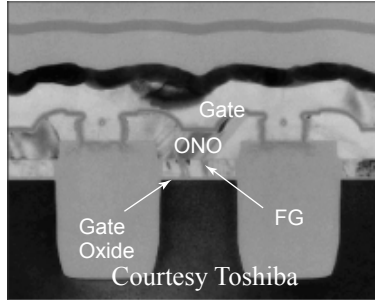
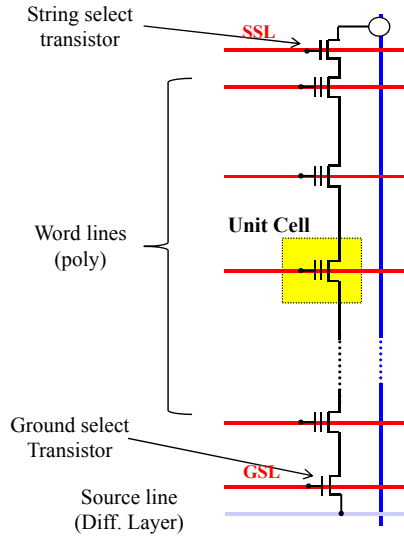
- ❑ Storage determined by charge on the floating gate
 - “0” = negative charge (extra electrons)
 - “1” = no charge
- ❑ Negative charge on floating gate “screens” normal gate, raising threshold
- ❑ Charge can take years to “leak off” once placed there
- ❑ **Multi Level** flash: different charge levels represent different values
 - We are “programming” V_t of the transistor

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Slide 2

NAND Flash Memory "String"



- All wordlines other than the one to be read are \gg "0" threshold, so they turn on.
- Wordline to be read has lower voltage:
 - If cell has "0" – no current
 - If cell has "1" – device is on

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Slide 3

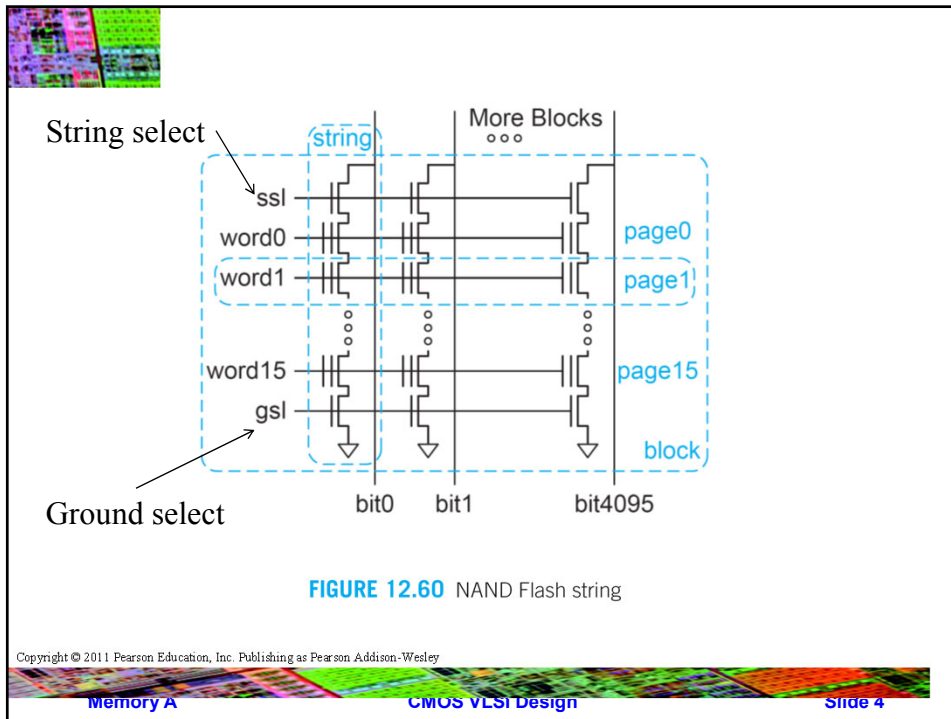


FIGURE 12.60 NAND Flash string

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Slide 4

8GB NAND Flash Memory

The diagram shows a cross-section of NAND Flash Memory. It features a grid of **Word lines** (green vertical bars) and **Bit line contacts** (yellow vertical bars). **Select transistors** are located at the intersections of these lines. **Active area** is indicated by arrows pointing to the grid. **STI** (Shallow Trench Isolation) is shown between the word lines. **Source line contact** is also labeled. To the right, a photograph of a memory chip shows two **Row Decoder** blocks, each labeled **32 Gb Plane 0** and **32 Gb Plane 1**, with **Sense Amp Peripheral Circuits** at the bottom.

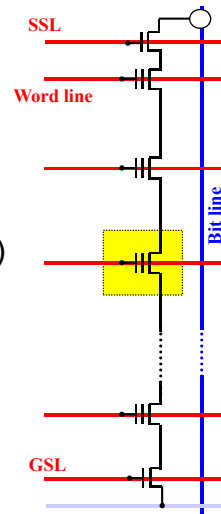
- 64 Gb (8GB) flash
- 2 independent **planes**
- 64K columns/pane
- Thus 64kbit **page**
- Each cell holds 4 bits
- Each **string** = 64 cells
- Each **block** has 256 pages
- Each pane has 2K blocks

Courtesy Toshiba

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Reading Data

- Precharge **bit lines**
- SSL & GSL set high
- Set **all word lines** **but** desired page to high enough to turn transistors on, regardless of state
- Set **word line for desired page** high enough to turn on IF NO CHARGE ("1") is present on floating gate
- Result depends on floating gate:
 - If no charge (1), all transistors on & bit line discharged
 - If negatively charged (0), bit line charge not disturbed



Question: Why do we have **string select** and **ground select** transistors?

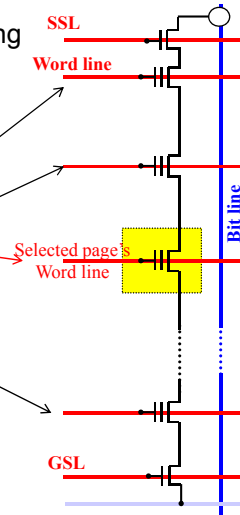
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Slide 6

Writing Data

- ❑ Cell “programmed” by placing electrons on floating gate
- ❑ Charge moved to/from via tunneling to substrate
- ❑ Writing is done a page at a time
 - Substrate held to ground
 - Word line for selected page raised very high (eg 20V) to *trigger tunneling*
 - Word line for all other pages at intermediate level (10V) guaranteed to turn transistors on, *but not tunnel*
 - Desired bit values placed on bit lines
 - If a “0” on bit line, then electrons tunnel to floating gate occurs



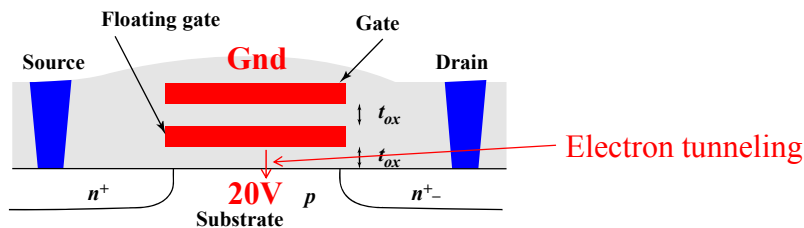
Note: we can ONLY WRITE ZEROS!!!

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Slide 7

Block Erasure



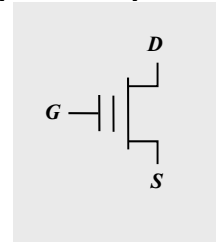
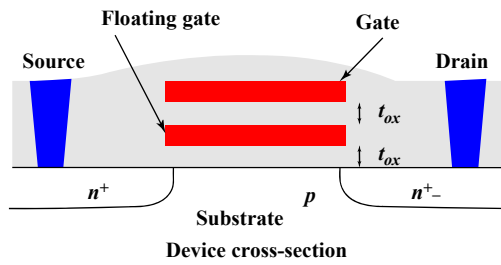
- ❑ If we can only write “0”s, how do we store “1”s?
- ❑ Answer: we “erase” all cells to 1 before writing and write only 0s
- ❑ **Erasing process:**
 - Set substrate very high (eg 20V)
 - Set all control gates to ground
 - Over time (ms), electrons on floating gates tunnel to substrate
- ❑ Cannot control substrate voltage of single transistors, so erase **all cells in a block** at the same time

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Slide 8

Non-Volatile Memories The Floating-gate transistor (FAMOS)



- **ERASE:** Raising substrate to high + voltage (eg 20V) with Gate at Ground, causes tunneling from floating gate to substrate, clearing floating gate of all charge
- **WRITE:** High + voltage on Control Gate, with substrate and ground, causes electrons to tunnel from substrate to floating gate, raising effective threshold of device, and representing a "0"
 - Different voltages can store different amounts of charge, changing threshold
- **READ** state by applying voltage (< "0" threshold) to control gate and seeing if current flows

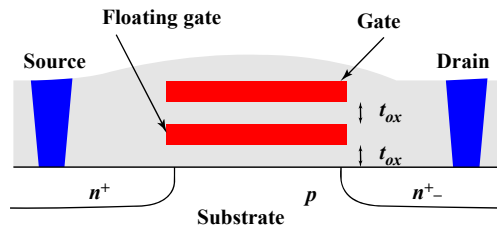
0 V	20 V	20 V	20 V	10 V
20 V	20 V	0 V	8 V	?
0 V	0 V	0 V	0 V	0 V
Erase	Inhibit Erase	Program 0	Do Not Program	Inhibit Program

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Slide 9

Summary



0 V	20 V	20 V	20 V	10 V
20 V	20 V	0 V	8 V	?
0 V	0 V	0 V	0 V	0 V
Erase	Inhibit Erase	Program 0	Do Not Program	Inhibit Program

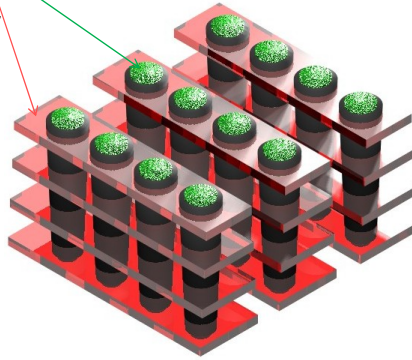
Memory A

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Slide 10

Flash is Going 3D

- **Charge Trap Flash** (CTF) instead of floating gate
 - Insulating film where charge is trapped
- **Strings** go vertical
 - **Transistors** literally “stacked” on top of each other

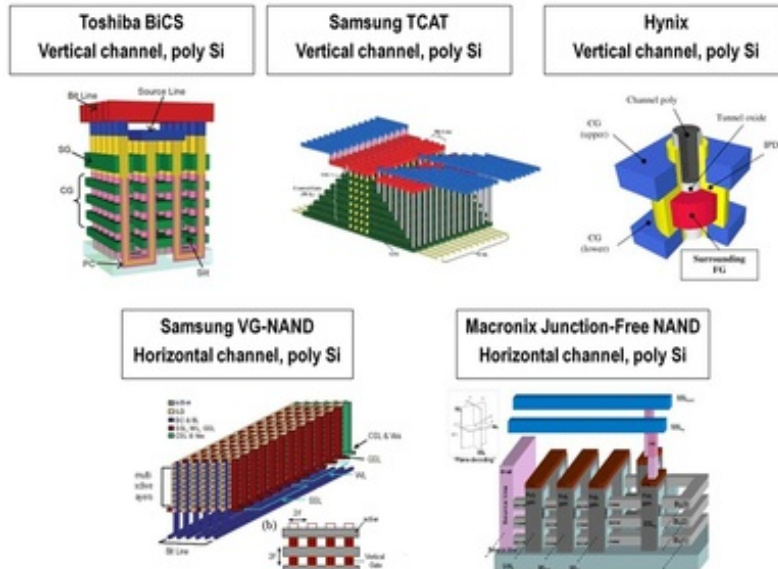


Memory A

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Slide 11

Flash Is Going 3D

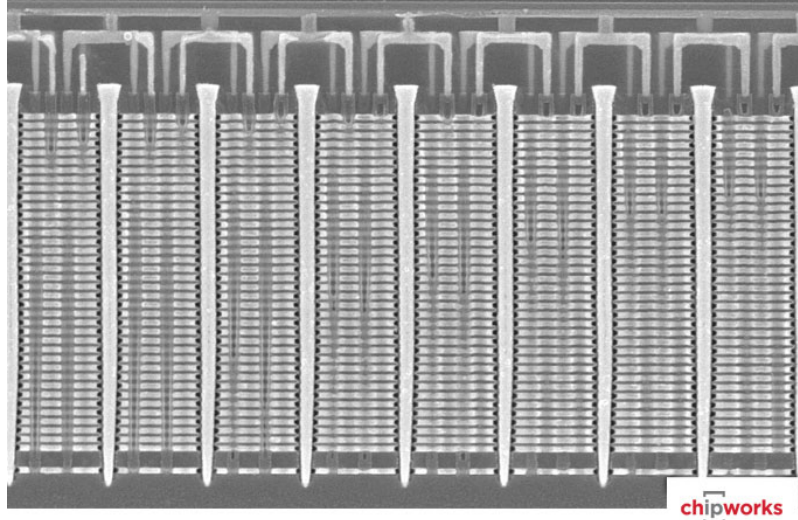


Memory A

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Slide 12

Flash Is Going 3D



Close-up image of V-NAND flash array

https://3uzly1fn22f2ax25i6snwb1-wpengine.netdna-ssl.com/wp-content/uploads/blog_9_fig1.jpg

Memory A

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Slide 13